Amendments to the Claims

1. (Currently Amended) A method for packaging a multi-chip module, comprising the steps of:

(a) connecting connection terminals of a tape of an anisotropic conductive adhesive film~~,~~ on which a circuit is patterned to bond pads of ~~the~~ a chip by applying ~~an~~ a first anisotropic conductive adhesive on the tape and using a first C4 process;

(b) applying an adhesive on an upper surface of the chip, folding the tape and attaching the folded tape to the upper surface of the chip;

(c) forming a plurality of ball terminals on a lower surface of the tape, the ball terminals being electrically connected to the connection terminals of the tape;

(d) manufacturing a plurality of individual chip scale packages by repeating the steps (a) to (c); and

(e) laminating the individual chip scale packages, wherein the ball terminals of an upper individual chip scale package ~~is~~ are electrically connected to the circuit ~~patterned~~ on the tape which covers a lower individual chip scale package.

2. (Currently Amended) The method of claim 1, further comprising the step of mounting the ball terminals of ~~the~~ a lowest one of the individual chip scale packages on a patterned circuit.

3. (Canceled)

4. (Canceled)

5. (Currently Amended) The method of claim 1, wherein, in the step (b), the ~~tape is attached to the chip by applying an~~ adhesive comprises a second anisotropic conductive adhesive ~~to the upper surface of the chip~~.

6. (Currently Amended) The method of claim 1, further comprising the step of providing an uppermost chip scale package on top of the laminated chip scale packages of step (e), wherein the tape covers only a lower surface of the uppermost ~~one of the~~ individual chip scale ~~packages~~package.

7. (New) The method of claim 6, wherein the step of providing an uppermost chip scale package comprises connecting connection terminals of a further tape of a further anisotropic conductive adhesive film on which a further circuit is patterned to bond pads of a further chip by applying a second adhesive on the tape, and forming a further plurality of ball terminals on a lower surface of the further tape, the further plurality of ball terminals being electrically connected to the connection terminals of the further tape.

8. (New) The method of claim 7, wherein the second adhesive comprises a third anisotropic conductive adhesive.

9. (New) The method of claim 7, wherein the step of connecting the connection terminals of the further tape uses a second C4 process.

10. (New) The method of claim 1, comprising the step of patterning the circuit on the tape.

11. (New) The method of claim 1, wherein, in step (b), the adhesive comprises a thermal conductive adhesive.

12. (New) The method of claim 2, wherein the patterned circuit comprises a printed circuit board.

Support for the Amendments

Support for the present amendments can be found throughout the specification, claims and figures as originally filed. Without being limited to such exemplary passages and/or other disclosures, support for the amendment to claim 1 can be found in claims 1, 3 and 4 as originally filed and in the specification on page 4, lines 3-7; support for the amendment to claim 6 can be found in the specification on page 6, lines 5-9; support for new claims 7-9 can be found in FIG. 5 and claims 1 and 6 as originally filed and in the support for the amendments to claims 1 and 6; support for new claim 10 can be found in claim 1 as originally filed and in the specification on page 4, lines 1-3, and page 6, lines 10-13; support for new claim 11 can be found in the specification on page 5, lines 1-4; and support for new claim 12 can be found in the specification on page 6, lines 1-4. Support for the remaining amendments to the specification and claims can be found in the context of the amended subject matter. Thus, no new matter is introduced by the present Amendment.

Claims 3 and 4 have been canceled. New Claims 7-12 (which depend directly or indirectly from Claim 1) have been added. Thus, Claims 1-2 and 5-12 are active in the present application.